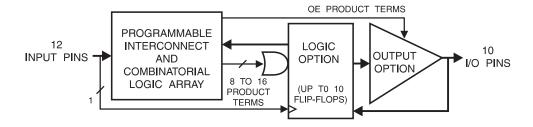
Features

- Third Generation Programmable Logic Structure
 - High-Density Replacement for Discrete Logic
- High-Speed Plus a New, Low-Power Version
- Increased Logic Flexibility
 - 42 Inputs and 20 Sum Terms
- Flexible Output Logic
 - 20 Flip-Flops 10 Extra
 - All Can Be Individually Buried or 10 Output Directly
 - Each has Individual Asynchronous Reset and Clock Terms
- Multiple Feedback Paths Provide for Buried State Machines and I/O Bus Compatibility
- Proven and Reliable High-Speed CMOS EPROM Process
 - 2000V ESD Protection
 - 200 mA Latchup Immunity
- Reprogrammable
 - Tested 100% for Programmability
- 24-pin, 300-mil Dual-In-line and 28-Lead Surface Mount Packages

Logic Diagram



Description

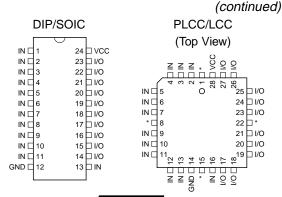
The ATV750(L) is 100% more powerful than most other programmable logic devices in 24-pin packages. Increased product terms, sum terms, and flip-flops translate into more usable gates.

Each of the ATV750(L)'s twenty-two logic pins can be used as an input. Ten of these can be used as input, output, or bi-directional I/O pins. All twenty flip-flops can be fed back into the array independently. This flexibility allows burying all of the sum terms and flip-flops.

There are 171 product terms available. A variable format is used to assign between four and eight product terms per sum term. There are two sum terms per output, providing added flexibility.

Pin Configurations

Pin Name	Function
IN	Logic Inputs
I/O	Bidirectional Buffers
*	No Internal Connection
VCC	+5V Supply





High Density UV Erasable Programmable Logic Device

ATV750 ATV750L

Rev. 0024E-05/98



The ATV750(L) has more flip-flops available than other PLDs in this density range. Complex state machines are easily implemented.

Product terms are available providing asynchronous resets, flip-flop clocks, and output enables. One reset and

Absolute Maximum Ratings

Temperature Under Bias	-55°C to + 125°C
Storage Temperature	-65°C to + 150°C
Voltage on Any Pin with Respect to Ground	2.0V to +7.0V ⁽¹⁾
Voltage on Input Pins with Respect to Ground During Programming	-2.0V to +14.0V ⁽¹⁾
Programming Voltage with Respect to Ground	-2.0V to +14.0V ⁽¹⁾
Integrated UV Erase Dose	7258 W.sec/cm ²

one clock term are provided per flip-flop, with one enable term per output. One product term provides a global synchronous preset. Register preload simplifies testing. The device has an internal power up clear function.

*NOTICE:

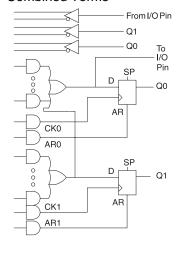
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Note:

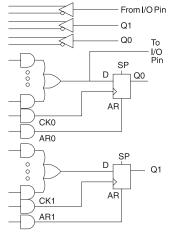
Minimum voltage is -0.6V DC, which may undershoot to -2.0V for pulses of less than 20 ns. Maximum output pin voltage is Vcc + 0.75V DC, which may overshoot to 7.0V for pulses of less than 20 ns.

Logic Options

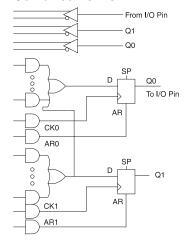
Combined Terms



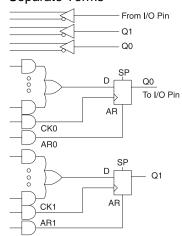
Separate Terms



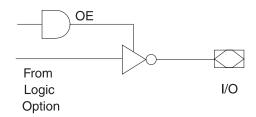
Combined Terms

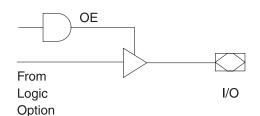


Separate Terms



Output Options





DC and AC Operating Conditions

		ATV750-20	ATV750/750L-25
	Com.	0°C - 70°C	0°C - 70°C
Operating Temperature (Case)	Ind.	-40°C - 85°C	-40°C - 85°C
	Mil.	-55°C - 125°C	-55°C - 125°C
V _{CC} Power Supply		5V ± 10%	5V ± 10%

DC Characteristics

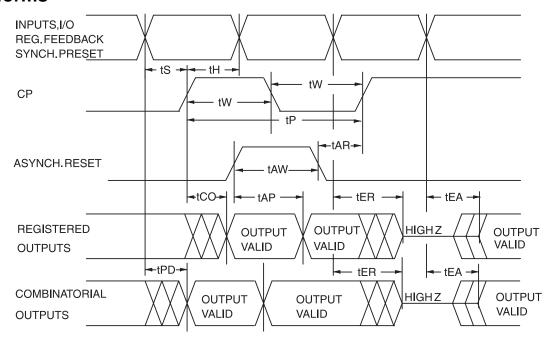
Symbol	Parameter	Condition			Min	Тур	Max	Units
I _{LI}	Input Load Current	$V_{IN} = -0.1 V$ to $V_{CC} + 1 V$					10	μΑ
I _{LO}	Output Leakage Current	$V_{OUT} = -0.1V$ to $V_{CC} + 0.1V$					10	μΑ
		$V_{CC} = MAX,$ $V_{IN} = GND,$ Outputs Open	ATV750	Com.			120	mA
,	Power Supply			Ind.,Mil.			140	mA
I _{CC}	Current		ATV750L	Com.		1.0	12	mA
				Ind.,Mil.		1.0	15	mA
I _{OS} ⁽¹⁾	Output Short Circuit Current	V _{OUT} = 0.5V					-120	mA
V _{IL}	Input Low Voltage	Input Low Voltage			-0.6		0.8	V
V _{IH}	Input High Voltage				2.0		V _{CC} + 0.75	V
			I _{OL} = 12 mA	Com.,Ind.			0.5	V
V _{OL}	Output Low Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL},$ $V_{CC} = MIN$	I _{OL} = 8 mA Mil.				0.5	V
			I _{OL} = 24 mA	, Com.			1.0	V
V	Output Lligh Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL},$	I _{OH} = -100 μ	A	V _{CC} - 0.3			V
V _{OH}	Output High Voltage	V _{CC} = MIN	I _{OH} = -4.0 m	nA	2.4			V

Note: 1. Not more than one output at a time should be shorted. Duration of short circuit test should not exceed 30 sec.





AC Waveforms⁽¹⁾

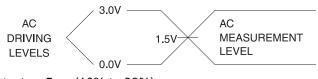


Note: 1. Timing measurement reference is 1.5V. Input AC driving levels are 0.0V and 3.0V, unless otherwise specified.

AC Characteristics

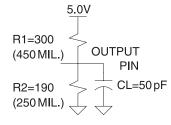
		ATV	750-20	ATV750	/750L-25	
Symbol	Parameter	Min	Max	Min	Max	Units
t _{PD}	Input or Feedback to Non-Registered Output		20		25	ns
t _{EA}	Input to Output Enable		20		25	ns
t _{ER}	Input to Output Disable		20		25	ns
t _{CO}	Clock to Output		20		22	ns
t _{CF}	Clock to Feedback	5	10	5	10	ns
t _S	Input Setup Time	10		12		ns
t _{SF}	Feedback Setup Time	5		7		ns
t _H	Hold Time	5		5		ns
t _P	Clock Period	18		22		ns
t _W	Clock Width	8		10		ns
F _{MAX}	Maximum Frequency		55		45	MHz
t _{AW}	Asynchronous Reset Width	15		20		ns
t _{AR}	Asynchronous Reset Recovery Time	15		20		ns
t _{AP}	Asynchronous Reset to Registered Output Reset		20		25	ns
t _{SP}	Setup Time, Synchronous Preset	12		15		ns

Input Test Waveforms and Measurement Levels



 t_R , $t_F < 5$ ns (10% to 90%)

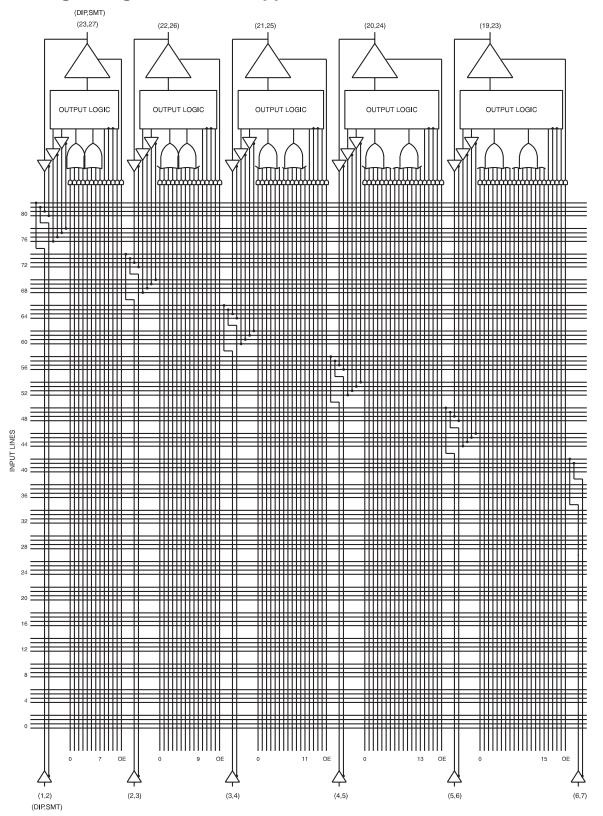
Output Test Loads



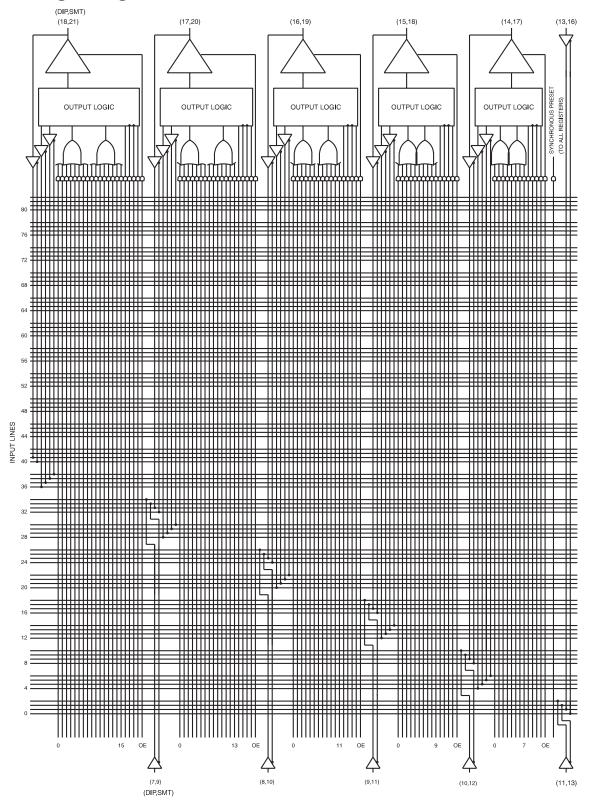




Functional Logic Diagram ATV750, Upper Half



Functional Logic Diagram ATV750, Lower Half



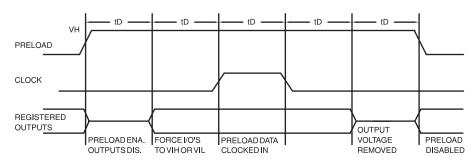




Preload of Registered Outputs

The ATV750's registers are provided with circuitry to allow loading of each register asynchronously with either a high or a low. This feature will simplify testing since any state can be forced into the registers to control test sequencing. A V_{IH} level on the I/O pin will force the register high; a V_{IL}

will force it low, independent of the output polarity. The preload state is entered by placing an 10.5V to 11.5V signal on pin 8 on DIPs, and pin 10 on SMPs. When the clock term is pulsed high, the data on the I/O pin is placed into the register chosen by the Select Pin.



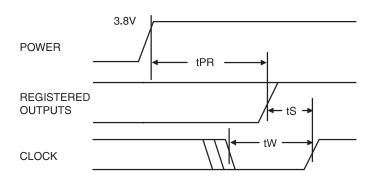
Level forced on registered output pin during PRELOAD cycle	Select Pin State	Register #1 state after cycle	Register#2 State after cycle
V _{IH}	Low	High	X
V_{IL}	Low	Low	X
V _{IH}	High	X	High
V _{IL}	High	X	Low

Power-Up Reset

The registers in the ATV750(L) are designed to reset during power up. At a point delayed slightly from V_{CC} crossing 3.8V, all registers will be reset to the low state. The output state will depend on the polarity of the output buffer.

This feature is critical for state machine initialization. However, due to the asynchronous nature of reset and the uncertainty of how $V_{\rm CC}$ actually rises in the system, the following conditions are required:

- 1. The V_{CC} rise must be monotonic,
- After reset occurs, all input and feedback setup times must be met before driving the clock term high, and
- 3. The signals from which the clock is derived must remain stable during t_{PR} .



Parameter	Description	Min	Тур	Max	Units
t _{PR}	Power-Up Reset Time		600	1000	ns

Pin Capacitance $(f = 1 \text{ MHz}, T = 25^{\circ}\text{C})^{(1)}$

	Тур	Max	Units	Conditions
C _{IN}	5	8	pF	$V_{IN} = 0V$
C _{OUT}	6	8	pF	V _{OUT} = 0V

Note: 1. Typical values for nominal supply voltage. This parameter is only sampled and is not 100% tested.

Using the ATV750's Many Advanced Features

The ATV750's flexibility puts more <u>usable</u> gates in 24-pins than other PLDs. The ATV750(L) starts with an architecture similar to the popular AT22V10, and adds several features:

• Asynchronous Clocks -

Each of the flip-flops in the ATV750(L) has a dedicated product term driving the clock. The user is no longer constrained to using one clock for all the registers. Buried state machines, counters, and registers can all coexist in one device, while running on separate clocks. The ATV750(L) clock period matches that of similar synchronous devices.

A Full Bank of 10 More Registers -

The ATV750(L) provides two flip-flops for each output macrocell - a total of 20. Each register has its own clock and reset product terms, as well as its own SUM term.

• Independent I/O Pin and Feedback Paths -

Each I/O pin on the ATV750(L) has a dedicated input path. Each of the 20 registers has individual feedback terms into the array. This feature, combined with individual product terms for each I/O's output enable, facilitates designs using bi-directional I/O buses.

Combinable Sum Terms -

Each output macrocell's two SUM terms can be combined in an OR gate before the output or the register. This provides up to 16 product terms per output or flipflop. This architecture increases the number of usable gates available.

Programming Software Support

Software which is capable of transforming Boolean equations, state machine descriptions and truth tables into JEDEC files for the ATV750(L) is available from several PLD software vendors. Please refer to the Software Support Information table in the *Programmable Logic Development Tools* section for more information.

Synchronous Preset and Asynchronous Reset

One synchronous preset line is provided for all 20 registers in the ATV750(L). The appropriate input signals to cause the internal clocks to go to a high state must be received during a synchronous preset. Appropriate setup and hold times must be met, as shown in the switching waveform diagram.

An individual asynchronous reset line is provided for each of the 20 flip-flops. Both master and slave halves of the flip-flops are reset when the input signals received combine so as to force the internal resets high.

Security Fuse Usage

A single fuse is provided to prevent unauthorized copying of the ATV750(L) fuse patterns. Once programmed, the output buffers will remain in a high impedance state during verify.

The security fuse should be programmed last, as its effect is immediate.

Erasure Characteristics

The entire memory array of an ATV750(L) is erased after exposure to ultraviolet light at a wavelength of 2537 Å. Complete erasure is assured after a minimum of 20 minutes exposure using 12,000 $\mu\text{W/cm}^2$ intensity lamps spaced one inch away from the chip. Minimum erase time for lamps at other intensity ratings can be calculated from the minimum integrated erasure dose of 15 W-sec/cm². To prevent unintentional erasure, an opaque label is recommended to cover the clear window on any UV erasable PLD which will be subjected to continuous fluorescent indoor lighting or sunlight.

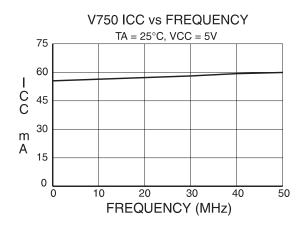
Atmel CMOS PLDs

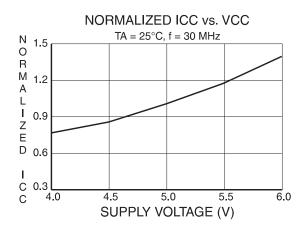
Atmel's Programmable Logic Devices utilize an advanced 1.5-micron CMOS EPROM technology. This technology's state of the art features are the optimum combination for PLDs:

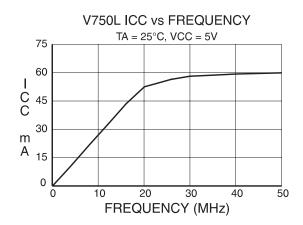
- CMOS technology provides high speed, low power, and high noise immunity.
- EPROM technology is the most cost effective method for producing PLDs - surpassing bipolar fusible link technology in low cost, while providing the necessary reprogrammability.
- EPROM reprogrammability, which is 100% tested before shipment, provides inherently better programmability and reliability than one-time fusible PLDs.
- Atmel's EPROM process has proven extremely reliable in the volume production of a full line of advanced EPROM memory products, from 64K to one-megabit devices.

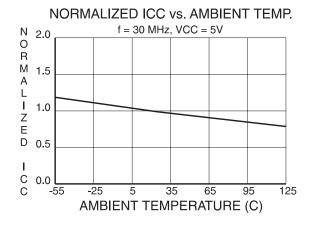












Ordering Information

t _{PD} (ns)	t _{co} (ns)	f _{MAX} (MHz)	Ordering Code	Package	Operation Range
20	20	55	ATV750-20JC	28J	Commercial
			ATV750-20PC	24P3	(0°C to 70°C)
			ATV750-20SC	24S	
			ATV750-20JI	28J	Industrial
			ATV750-20PI	24P3	(-40°C to 85°C)
			ATV750-20SI	24S	
			ATV750-20DM	24DW3	Military
			ATV750-20GM	24D3	(-55°C to 125°C)
			ATV750-20LM	28LW	
			ATV750-20NM	28L	
			ATV750-20DM/883	24DW3	Military/883C
			ATV750-20GM/883	24D3	(-55°C to 125°C)
			ATV750-20LM/883	28LW	
			ATV750-20NM/883	28L	
25	22	45	ATV750-25JC	28J	Commercial
			ATV750-25PC	24P3	(0°C to 70°C)
			ATV750-25SC	24S	
			ATV750-25JI	28J	Industrial
			ATV750-25PI	24P3	(-40°C to 85°C)
			ATV750-25SI	24S	
			ATV750-25DM	24DW3	Military
			ATV750-25GM	24D3	(-55°C to 125°C)
			ATV750-25LM	28LW	
			ATV750-25NM	28L	
			ATV750-25DM/883	24DW3	Military/883C
			ATV750-25GM/883	24D3	(-55°C to 125°C)
			ATV750-25LM/883	28LW	Class B, Fully Compliant
			ATV750-25NM/883	28L	
20	20	55	5962-88726 04 LA	24DW3	Military/883C
			5962-88726 04 3X	28LW	(-55°C to 125°C)
			5962-94524 03 MLA	24D3	Class B, Fully Compliant
			5962-94524 03 M3X	28L	
25	22	45	5962-88726 03 LA	24DW3	Military/883C
			5962-88726 03 3X	28LW	(-55°C to 125°C)
			5962-94524 02 MLA	24D3	Class B, Fully Compliant
			5962-94524 02 M3X	28L	





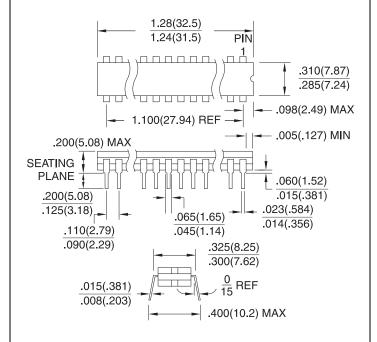
Ordering Information (Continued)

t _{PD} (ns)	t _{co} (ns)	f _{MAX} (MHz)	Ordering Code	Package	Operation Range
25	22	45	ATV750L-25JC	28J	Commercial
25	22	45	ATV750L-259C ATV750L-25PC	24P3	
				_	(0°C to 70°C)
			ATV750L-25SC	24S	
			ATV750L-25JI	28J	Industrial
			ATV750L-25PI	24P3	(-40°C to 85°C)
			ATV750L-25SI	24S	
			ATV750L-25DM	24DW3	Military
			ATV750L-25GM	24D3	(-55°C to 125°C)
			ATV750L-25LM	28LW	
			ATV750L-25NM	28L	
			ATV750L-25DM/883	24DW3	Military/883C
			ATV750L-25GM/883	24D3	(-55°C to 125°C)
			ATV750L-25LM/883	28LW	Class B, Fully Compliant
			ATV750L-25NM/883	28L	
25	22	45	5962-88726 07 LX	24DW3	Military/883C
			5962-88726 07 3X	28LW	(-55°C to 125°C)
			5962-94524 05 MLA	24D3	Class B, Fully Compliant
			5962-94524 05 M3X	28L	

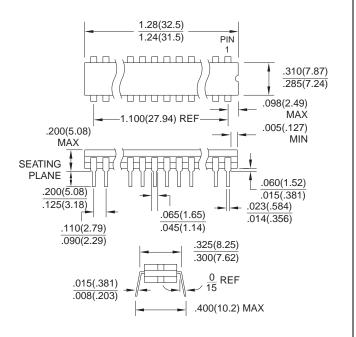
	Package Type
24DW3	24-Lead, 0.300" Wide, Windowed, Ceramic Dual In-line Package (Cerdip)
24D3	24-Lead, 0.300" Wide, Non-Windowed (OTP) Ceramic Dual In-line Package (Cerdip)
28J	28-Lead, Plastic J-Leaded Chip Carrier OTP (PLCC)
28LW	28-Pad, Windowed, Ceramic Leadless Chip Carrier (LCC)
28L	28-Pad, Non-Windowed, Ceramic Leadless Chip Carrier OTP (LCC)
24P3	24-Lead, 0.300" Wide, Plastic Dual In-line Package OTP (PDIP)
24S	24-Lead, 0.300" Wide, Plastic Gull Wing Small Outline OTP (SOIC)

Packaging Information

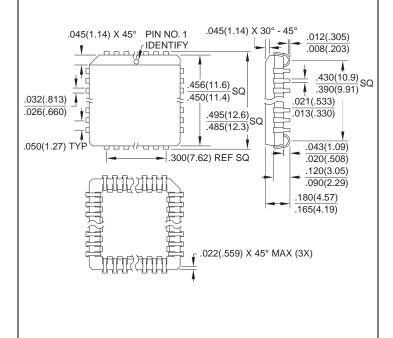
24DW3, 24-Lead, 0.300" Wide, Windowed, Ceramic Dual In-line Package (Cerdip) Dimensions in Inches and (Millimeters)



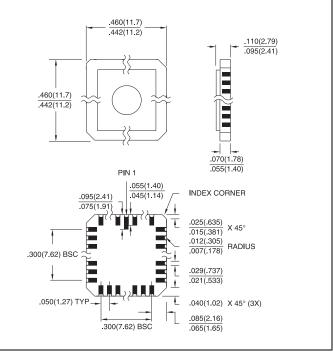
24D3, 24-Lead, 0.300" Wide, Non-Windowed (OTP) Ceramic Dual In-line Package (Cerdip) Dimensions in Inches and (Millimeters)



28J, 28-Lead, Plastic J-Leaded Chip Carrier OTP (PLCC) Dimensions in Inches and (Millimeters)



28LW, 28-Pad, Windowed, Ceramic Leadless Chip Carrier (LCC) Dimensions in Inches and (Millimeters)



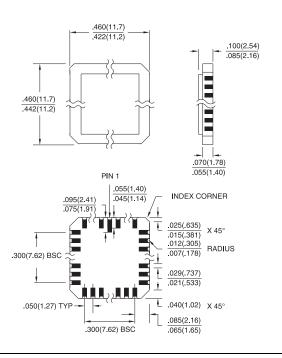




Packaging Information

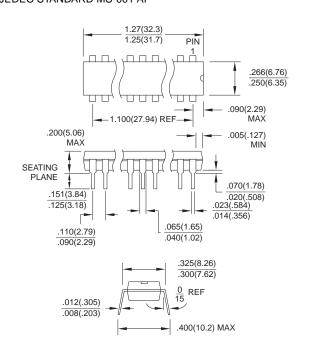
28L, 28-Pad, Non-Windowed, Ceramic Leadless Chip Carrier OTP (LCC)

Dimensions in Inches and (Millimeters)



24P3, 24-Lead, 0.300" Wide, Plastic Dual Inline Package OTP (PDIP) Dimensions in Inches and (Millimeters)

JEDEC STANDARD MS-001 AF



24S, 24-Lead, 0.300" Wide, Plastic Gull Wing Small Outline OTP (SOIC)

Dimensions in Inches and (Millimeters)

